TECHNICAL DATA SHEET
TDS #: RP 30
CYANOACRYLATE ADHESIVE
REVISED: DECEMBER/2010

ADVENT PERFORMANCE SERIES
RP 30 CYANOACRYLATE ADHESIVE
GENERAL PURPOSE BONDING

DESCRIPTION:
RP 30 is a low viscosity, rapid curing, cyanoacrylate adhesive. It is designed to bond a wide range of similar and dissimilar materials. Handling strength in most applications is in 5 to 10 seconds. Can be post applied.

PHYSICAL PROPERTIES:
Color: Clear
Viscosity: 30 cps
Specific Gravity: 1.05
Base: Ethyl

PERFORMANCE PROPERTIES:

<table>
<thead>
<tr>
<th>Substrate</th>
<th>Fixture Time</th>
<th>Bond Strength</th>
</tr>
</thead>
<tbody>
<tr>
<td>Steel</td>
<td>&lt; 20 Seconds</td>
<td>&gt; 2100 psi</td>
</tr>
<tr>
<td>Aluminum</td>
<td>&lt; 15 Seconds</td>
<td>&gt; 1750 psi</td>
</tr>
<tr>
<td>Neoprene</td>
<td>&lt; 5 Seconds</td>
<td>&gt; 750 psi</td>
</tr>
<tr>
<td>ABS</td>
<td>&lt; 10 Seconds</td>
<td>&gt; 900 psi</td>
</tr>
<tr>
<td>PVC</td>
<td>&lt; 5 Seconds</td>
<td>&gt; 900 psi</td>
</tr>
<tr>
<td>Polycarbonate</td>
<td>&lt; 30 Seconds</td>
<td>&gt; 900 psi</td>
</tr>
<tr>
<td>Phenolic</td>
<td>&lt; 10 Seconds</td>
<td>&gt; 850 psi</td>
</tr>
</tbody>
</table>

NOTE: Method used, ISO 4587.

What we bond:
ABS
Acrylic
Aluminum
Bakelite
Brass
Chloroprene
Chrome
Cooper
EPDM
Fiberglass
Latex
Leather
Natural Rubber
Polycarbonate
PVC
SBR
Steel
Valox
Wood

CHEMICAL/SOLVENT RESISTANCE:
% OF STRENGTH RETAINED AFTER AGING FOR 500 HOURS

- GASOLINE @ 22°C: 100%
- ISOPROPANOL @ 22°C: 100%
- ETHANOL @ 22°C: 100%
- FREON TA @ 22°C: 100%
- MOTOR OIL @ 40°C: 100%
- POLYCARBONATE 40°C @ 95% RH: 100%

DIRECTIONS FOR USE:
For optimum results parts should be clean and free from any contamination on the bonding surface. If parts do not mate flush together use a higher viscosity product to compensate for the gap. Any excess adhesive can be removed using Remove Debonder.

STORAGE:
Store product in unopened containers, out of direct sunlight, in a dry location. Material should be stored at or below 22°C. For extended shelf life unopened containers of the product may be refrigerated.

FACTORS AFFECTING CURE SPEED:
GAP: Thin bond line results in faster cure speed. Larger gaps will lengthen cure speed.
HUMIDITY: Cure and fixture times can be influenced by the humidity conditions at the time of assembly. The higher the RH the faster cure and fixture times will be. Fixture time data based on our testing is conducted at 50% relative humidity.

ELECTRICAL PROPERTIES:
Dielectric Constant: ASTM D 150 Dissipation Factor
1 KHz: 2 to 3.50/ < 0.02
Volume Resistivity: ASTM D 257: 2 x 10^15 to 10 x 10^15

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